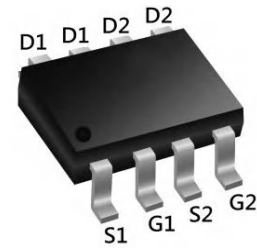


## Description

The XXW4828 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.



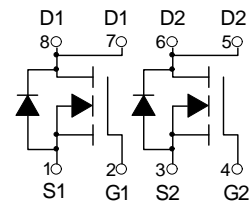
SOP-8

## General Features

$V_{DS} = 60V$   $I_D = 6.5A$   
 $R_{DS(ON)} < 36m\Omega @ V_{GS}=10V$   
 $R_{DS(ON)} < 48m\Omega @ V_{GS}=4.5V$

## Application

Battery protection  
 Load switch  
 Uninterruptible power supply



Dual N-Channel MOSFET

## Absolute Maximum Ratings@ $T_J=25^\circ C$ (unless otherwise specified)

| Symbol                 | Parameter   | Rating     | Units        |
|------------------------|---|------------|--------------|
| $V_{DS}$               | Drain-Source Voltage                                      | 60         | V            |
| $V_{GS}$               | Gate-Source Voltage                                       | $\pm 20$   | V            |
| $I_D @ T_A=25^\circ C$ | Drain Current, $V_{GS} @ 4.5V^3$                          | 6.5        | A            |
| $I_D @ T_A=70^\circ C$ | Drain Current, $V_{GS} @ 4.5V^3$                          | 5          | A            |
| $I_{DM}$               | Pulsed Drain Current <sup>1</sup>                         | 30         | A            |
| $P_D @ T_A=25^\circ C$ | Total Power Dissipation                                   | 2.1        | W            |
| $T_{STG}$              | Storage Temperature Range                                 | -55 to 150 | $^\circ C$   |
| $T_J$                  | Operating Junction Temperature Range                      | -55 to 150 | $^\circ C$   |
| $R_{thj-a}$            | Maximum Thermal Resistance, Junction-ambient <sup>3</sup> | 60         | $^\circ C/W$ |

**Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

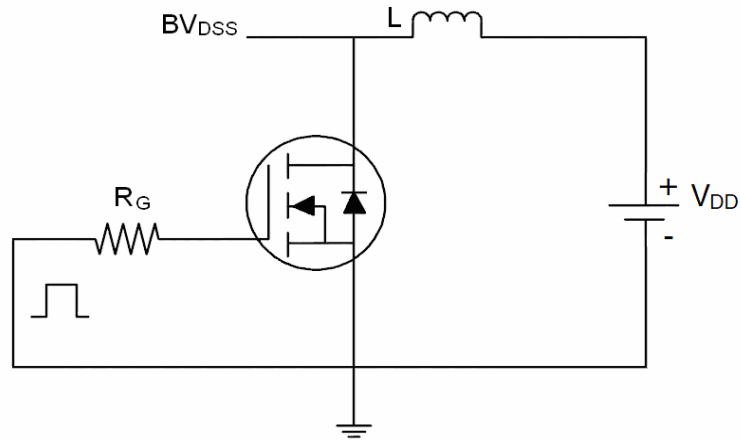
| Parameter                                 | Symbol              | Condition  | Min | Typ  | Max  | Unit |
|---|---------------------|--|-----|------|------|------|
| <b>Off Characteristics</b>                |                     |  |     |      |      |      |
| Drain-Source Breakdown Voltage            | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V, I <sub>D</sub> =250μA   | 60  | 69   | -    | V    |
| Zero Gate Voltage Drain Current           | I <sub>DSS</sub>    | V <sub>DS</sub> =60V, V <sub>GS</sub> =0V  | -   | -    | 1    | μA   |
| Gate-Body Leakage Current                 | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V   | -   | -    | ±100 | nA   |
| <b>On Characteristics</b> (Note 3)        |                     |  |     |      |      |      |
| Gate Threshold Voltage                    | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA                                 | 1.0 | 1.4  | 2.0  | V    |
| Drain-Source On-State Resistance          | R <sub>DS(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =6A   |     | 32   | 36   | mΩ   |
|   |                     | V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A  |     | 34   | 48   | mΩ   |
| Forward Transconductance                  | g <sub>FS</sub>     | V <sub>DS</sub> =5V, I <sub>D</sub> =6A  |     | 20   | -    | S    |
| <b>Dynamic Characteristics</b> (Note 4)   |                     |  |     |      |      |      |
| Input Capacitance                         | C <sub>iss</sub>    | V <sub>DS</sub> =25V, V <sub>GS</sub> =0V,<br>F=1.0MHz                                   |     | 1920 |      | PF   |
| Output Capacitance                        | C <sub>oss</sub>    |  |     | 155  |      | PF   |
| Reverse Transfer Capacitance              | C <sub>rss</sub>    |  |     | 116  |      | PF   |
| <b>Switching Characteristics</b> (Note 4) |                     |  |     |      |      |      |
| Turn-on Delay Time                        | t <sub>d(on)</sub>  | V <sub>DS</sub> =30V, R <sub>L</sub> =4.7Ω<br>V <sub>GS</sub> =10V, R <sub>GEN</sub> =3Ω | -   | 8    | -    | nS   |
| Turn-on Rise Time                         | t <sub>r</sub>      |  | -   | 5    | -    | nS   |
| Turn-Off Delay Time                       | t <sub>d(off)</sub> |  | -   | 29   | -    | nS   |
| Turn-Off Fall Time                        | t <sub>f</sub>      |  | -   | 6    | -    | nS   |
| Total Gate Charge                         | Q <sub>g</sub>      | V <sub>DS</sub> =30V, I <sub>D</sub> =6A,<br>V <sub>GS</sub> =10V                        | -   | 50   | -    | nC   |
| Gate-Source Charge                        | Q <sub>gs</sub>     |  | -   | 8    | -    | nC   |
| Gate-Drain Charge                         | Q <sub>gd</sub>     |  | -   | 16   | -    | nC   |
| <b>Drain-Source Diode Characteristics</b> |                     |  |     |      |      |      |
| Diode Forward Voltage (Note 3)            | V <sub>SD</sub>     | V <sub>GS</sub> =0V, I <sub>S</sub> =6A  | -   | -    | 1.2  | V    |
| Diode Forward Current (Note 2)            | I <sub>S</sub>      |  | -   | -    | 7    | A    |
| Reverse Recovery Time                     | t <sub>rr</sub>     | T <sub>J</sub> = 25°C, I <sub>F</sub> = 7A<br>di/dt = 100A/μs (Note 3)                   | -   | 35   | -    | nS   |
| Reverse Recovery Charge                   | Q <sub>rr</sub>     |  | -   | 43   | -    | nC   |
| Forward Turn-On Time                      | t <sub>on</sub>     | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)                     |     |      |      |      |

**Notes:**

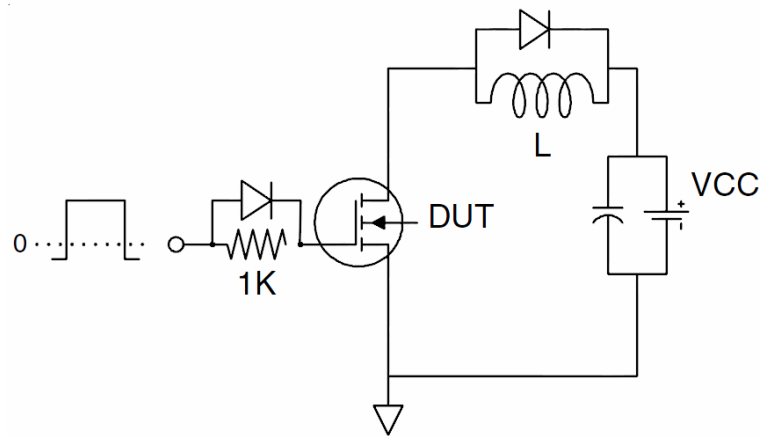
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

**Test Circuit**

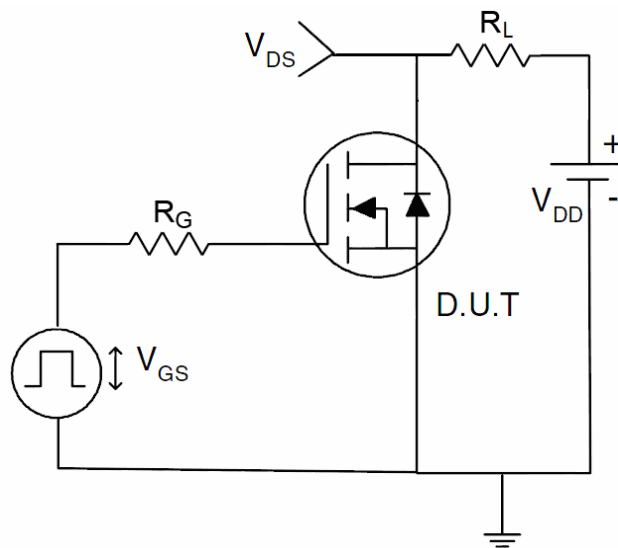
**1)  $E_{AS}$  test Circuits**

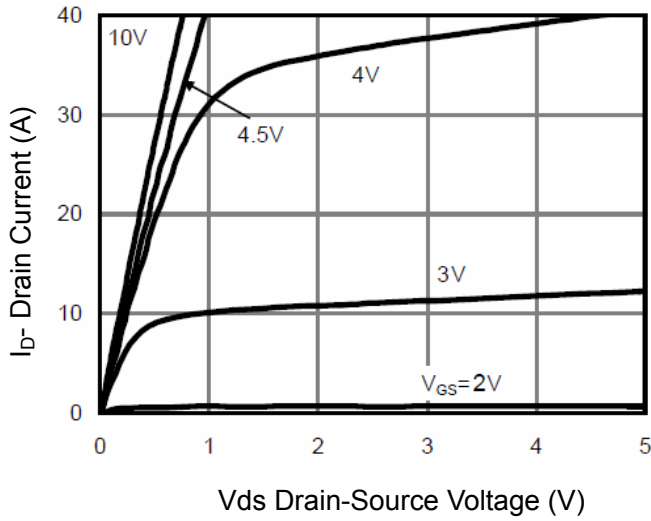
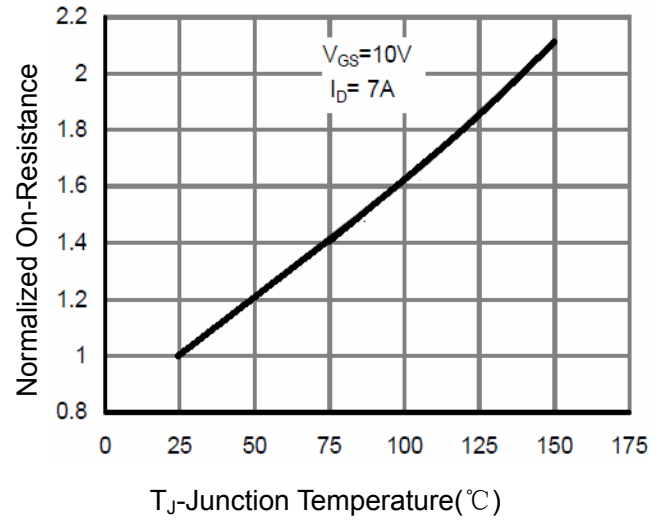
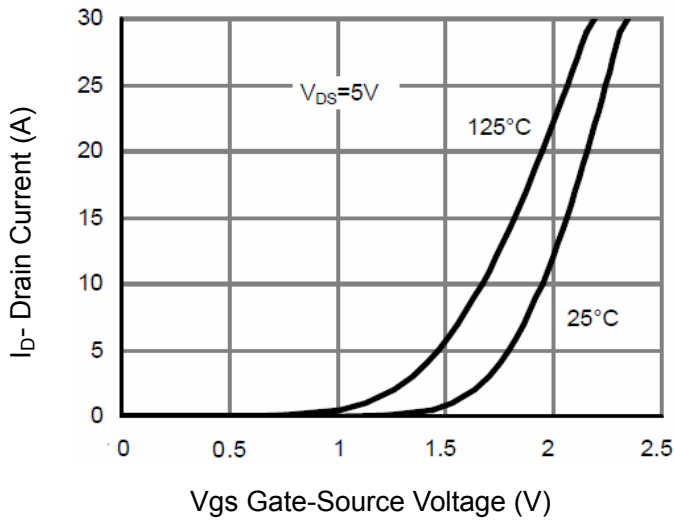
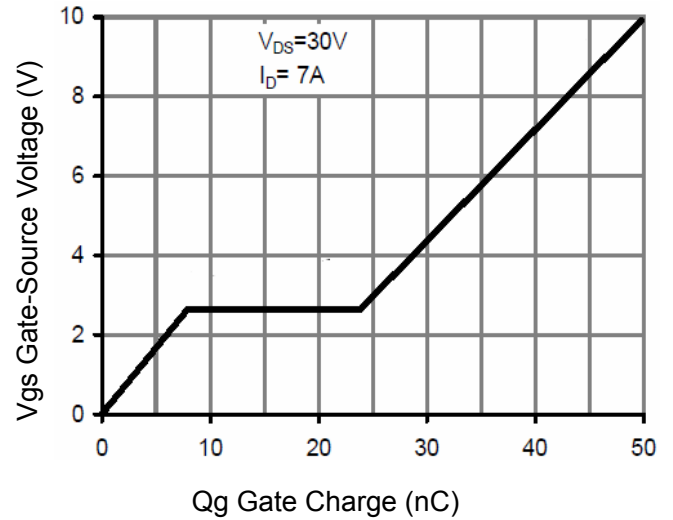
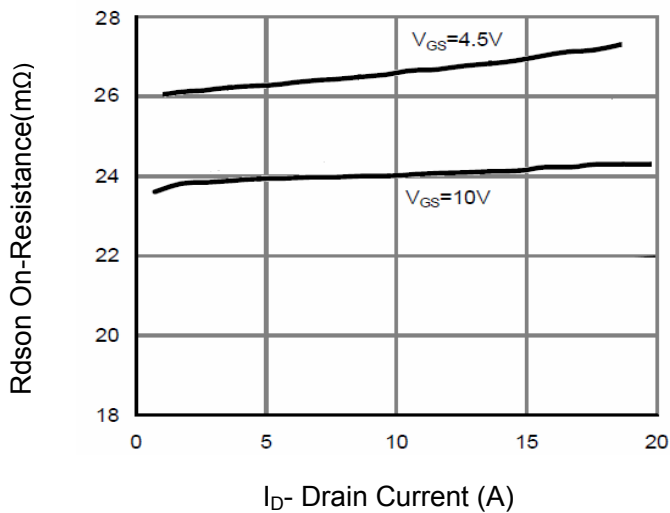
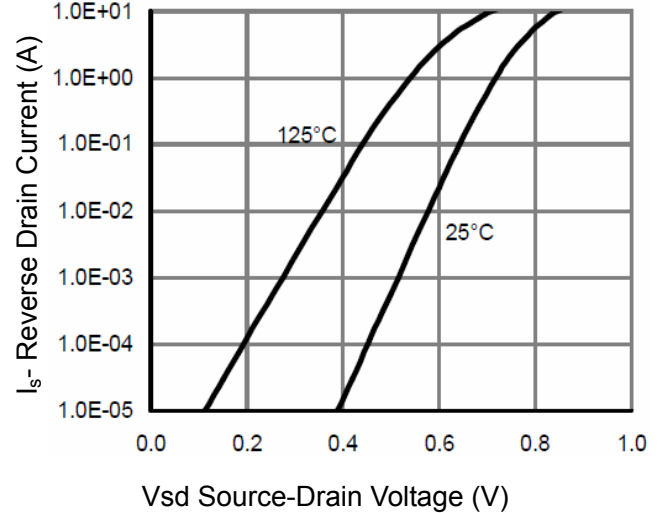


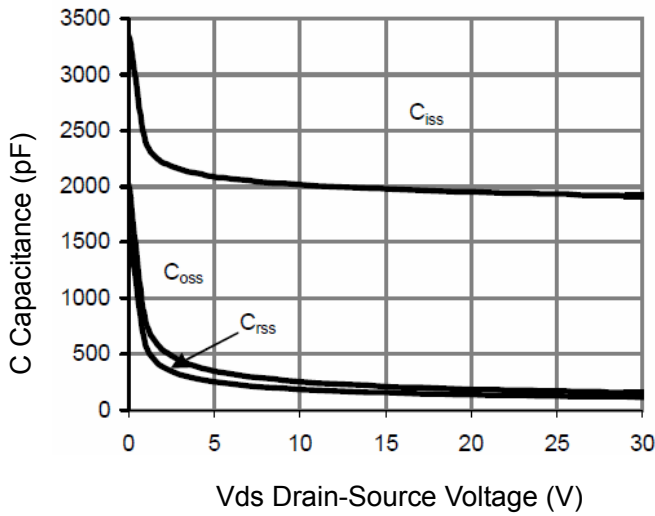
**2) Gate charge test Circuit**



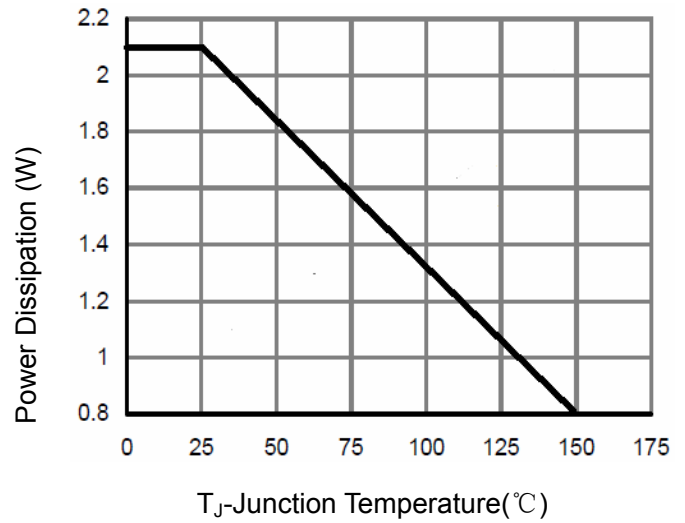
**3) Switch Time Test Circuit**



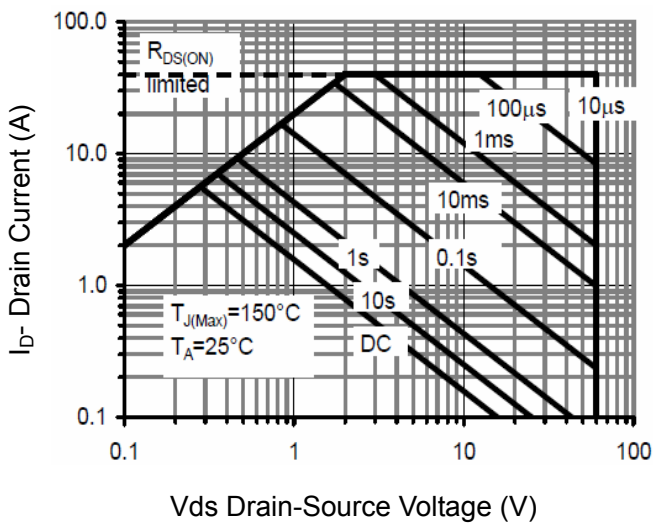
**Typical Electrical and Thermal Characteristics (Curves)**

**Figure 1 Output Characteristics**

**Figure 4 Rdson-Junction Temperature**

**Figure 2 Transfer Characteristics**

**Figure 5 Gate Charge**

**Figure 3 Rdson- Drain Current**

**Figure 6 Source- Drain Diode Forward**



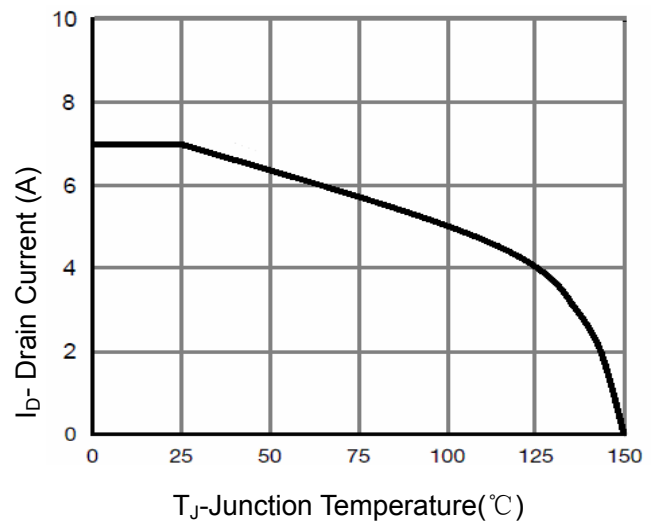
**Figure 7 Capacitance vs Vds**



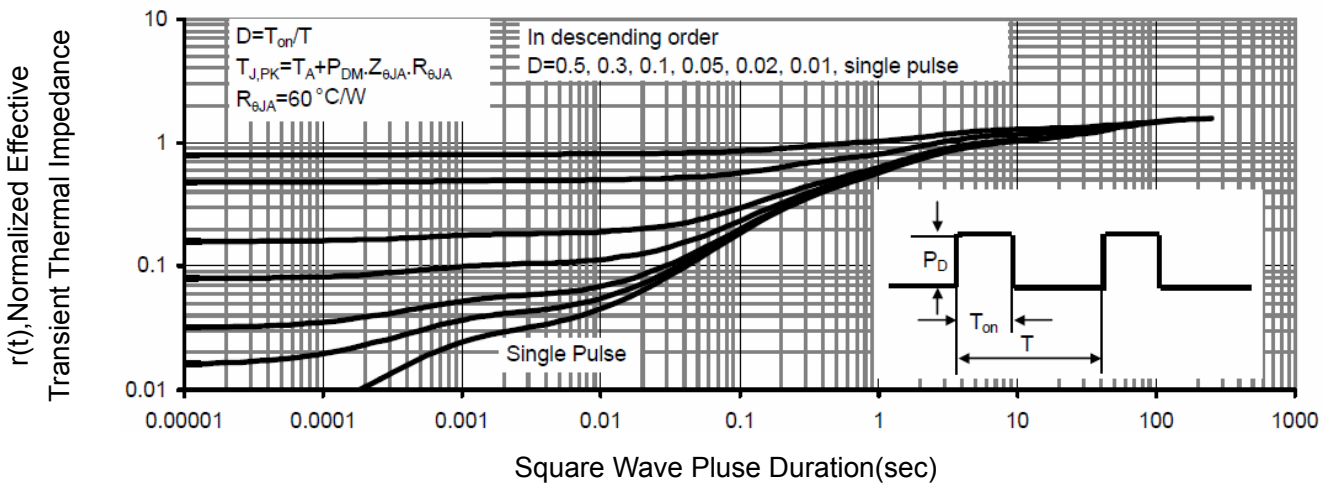
**Figure 9 Power De-rating**



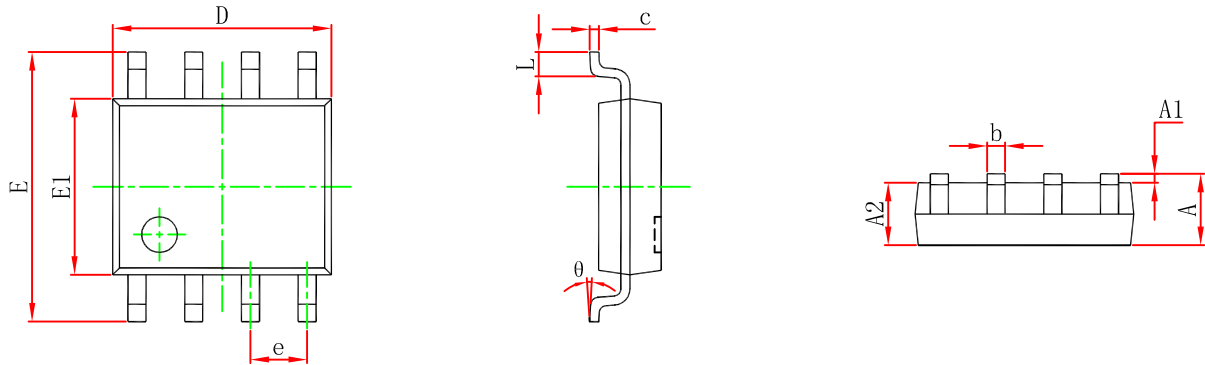
**Figure 8 Safe Operation Area**



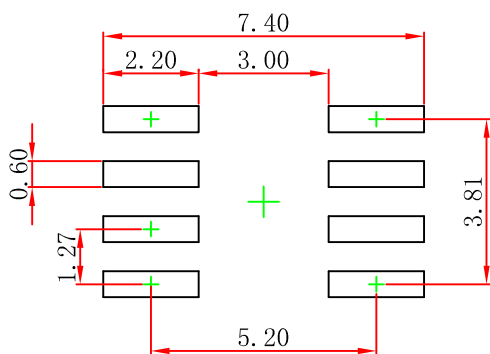
**Figure 10 Current De-rating**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

**SOP-8 Package Outline Dimensions**


| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min                       | Max   | Min                  | Max   |
| A      | 1.350                     | 1.750 | 0.053                | 0.069 |
| A1     | 0.100                     | 0.250 | 0.004                | 0.010 |
| A2     | 1.350                     | 1.550 | 0.053                | 0.061 |
| b      | 0.330                     | 0.510 | 0.013                | 0.020 |
| c      | 0.170                     | 0.250 | 0.007                | 0.010 |
| D      | 4.800                     | 5.000 | 0.189                | 0.197 |
| e      | 1.270 (BSC)               |       | 0.050 (BSC)          |       |
| E      | 5.800                     | 6.200 | 0.228                | 0.244 |
| E1     | 3.800                     | 4.000 | 0.150                | 0.157 |
| L      | 0.400                     | 1.270 | 0.016                | 0.050 |
| θ      | 0°                        | 8°    | 0°                   | 8°    |



Note:  
 1. Controlling dimension: in millimeters.  
 2. General tolerance:  $\pm 0.05\text{mm}$ .  
 3. The pad layout is for reference purposes only.